

EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	329	moriceau-hubert.in. or aspar-bernard.in. or margail-jacques.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/12/07 10:48
S2	3782	(noncontinuous\$ or (non adj continuous\$) or ("non-continuous\$")) with (film or layer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/12/07 10:49
S3	1074	S2 semiconductor	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/12/07 10:50
S4	712	S2 ("438".clas. or "257".clas.)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/12/07 10:51
S5	30	("6156215" "20040222500" "6146979" "6417075" "6974759" "20020145489" "20030077885" "6764936" "5259247" "6198159" "20050112845" "6429094" "20050042842" "20030119279" "6902987").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/12/07 13:10
S6	4360	(second with substrate) with rough\$	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/12/07 14:09
S7	3128	(second with substrate) with rough\$ with surface	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/12/07 14:10
S8	2300	(second with substrate) with rough\$	US-PGPUB;	AND	ON	2011/12/07

		near2 surface	USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB			14:10
S9	575	438/406.ccls.	US- PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/12/07 14:10
S10	9	S8 S9	US- PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/12/07 14:11
S11	311372	(rough\$ or RMS) near2 surface	US- PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/12/07 14:17
S12	375932	(rough\$ or RMS or uneven or cragged or craggy or jagged or ridged or rocky or ("not" or non) adj uniform)) near2 surface	US- PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/12/07 14:18
S13	145	S9 S12	US- PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/12/07 14:18
S14	2511	438/455.ccls.	US- PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/12/07 14:44
S15	1747	438/459.ccls.	US- PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/12/07 14:44
S16	490	438/311.ccls.	US- PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT;	AND	ON	2011/12/07 14:44

			IBM_TDB			
S17	758	438/756.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/12/07 14:44
S18	3782	S14 or S15	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/12/07 14:44
S19	968	S18 S12	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/12/07 14:44
S20	899	S19 not S13	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/12/07 14:44
S21	64	S17 S12	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/12/07 16:54
S22	575	438/406.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/12/12 14:57
S23	376210	(rough\$ or RMS or uneven or cragged or craggy or jagged or ridged or rocky or ("not" or non) adj uniform)) near2 surface	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/12/12 14:57
S24	145	S22 S23	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/12/12 14:57
S25	5927	((first or second) with (substrate or wafer or plate or semiconductor)) with rough\$ near2 surface	US-PGPUB; USPAT; USOCR; FPRS;	AND	ON	2011/12/12 15:15

			EPO; JPO; DERWENT; IBM_TDB			
S26	1556362	second with (substrate or wafer or plate or semiconductor)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/12/12 15:17
S27	5298	S25 S26	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/12/12 15:17
S28	3859	S25 with S26	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/12/12 15:17
S29	1011	S28.dlm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/12/12 15:17
S30	370995	second near (substrate or wafer or plate or semiconductor)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/12/12 15:18
S31	451782	first near (substrate or wafer or plate or semiconductor)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/12/12 15:18
S32	1402	((first or second) near (substrate or wafer or plate or semiconductor)) with rough\$ near2 surface	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/12/12 15:19
S33	366	S32 same (etch\$ or remov\$5 or eliminat\$)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/12/12 15:20
S34	153	S31 with S32 with (bond\$4 or attach\$4 or adher\$7)	US-PGPUB; USPAT;	AND	ON	2011/12/12 15:23

			USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB			
S35	34	("20020017133" "20020071169" "20020195417" "20040065638" "20040102021" "20040177689" "20050081633" "20050082252" "20050166677" "20050170656" "20050172717" "20060014358" "20060101912" "20060219006" "20070012653" "20080048211" "20080115579" "20100009514" "20100026779" "6084257" "6316796" "6773942" "6892575" "6939473" "6946314" "6988408" "7104129" "7223624" "7238621" "7247246" "7250112" "7335527" "7458263" "7621183").PN. OR ("7745308").URPN.	US- PGPUB; USPAT; USOCR	AND	ON	2011/12/12 15:50
S36	1170	438/50.ccls.	US- PGPUB; USPAT; USOCR	AND	ON	2011/12/12 15:55
S37	863	438/51.ccls.	US- PGPUB; USPAT; USOCR	AND	ON	2011/12/12 15:55
S38	978	438/52.ccls.	US- PGPUB; USPAT; USOCR	AND	ON	2011/12/12 15:56
S39	924	438/53.ccls.	US- PGPUB; USPAT; USOCR	AND	ON	2011/12/12 15:56
S40	3045	S36 or S37 or S38 or S39	US- PGPUB; USPAT; USOCR	AND	ON	2011/12/12 15:56
S41	5	S40 S32	US- PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/12/12 15:57
S42	920	S40 S30	US- PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/12/12 16:00
S43	726	S40 S30 S31	US- PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/12/12 16:00
S44	2	S40 S34	US- PGPUB; USPAT; USOCR;	AND	ON	2011/12/12 16:00

			FPRS; EPO; JPO; DERWENT; IBM_TDB			
S45	556	S40 (S30 same S31)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/12/12 16:02
S46	202	S45 sacrificial	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/12/12 16:49
S47	2511	438/455.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/12/12 17:05
S48	1747	438/459.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/12/12 17:05
S49	490	438/311.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/12/12 17:05
S50	758	438/756.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/12/12 17:05
S51	5263	S47 or S48 or S49 or S50 or S22	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/12/12 17:05
S52	11723520	@pd>="20070511"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/12/12 17:05
S53	1859	S51 S52	US-PGPUB;	AND	ON	2011/12/12

			USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB		17:05
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